

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claim 1-9 (canceled)

Claim 10 (currently amended) A method eliminating moisture from electronic components, the method comprising:

- storing electronic components in a storage area;
- maintaining a warm and dry atmosphere in the storage area by enclosing the storage area and injecting a warm and dry gas into the storage area at a flow rate and temperature which are controlled to eliminate moisture from the components in the storage area, wherein the resulting moisture level in the components accounts for 0.1% or less of the weight of the electronic components; and
- ~~removing about 0.1% or more of the weight of the components by elimination of moisture while the components are stored in the storage area.~~

Claim 11 (original) The method of Claim 10, wherein the component storage area is a feeder cart for storing the components.

Claim 12 (original) The method of Claim 10, wherein the component storage area is a cabinet receiving at least one feeder cart for storing the components.

Claim 13 (original) The method of Claim 10, wherein the component storage area is a storage cabinet for storing the components.

Claim 14 (original) The method of Claim 10, wherein the temperature control system controls the temperature of the dry gas to about 10°C to about 60°C.

Claim 15 (original) The method of Claim 10, wherein the temperature control system controls the temperature of the dry gas to about 20°C to about 50°C.

Claim 16 (original) The method of Claim 10, wherein a flow rate of the dry gas delivered to the storage area is controlled by a control system including a humidity sensor within the component storage area.

Claim 17 (cancelled)